MA2J1110G

Silicon epitaxial planar type

For switching circuits

■ Features

- Allowing high-density mounting
- Short reverse recovery time t_{rr}
- ullet Small terminal capacitance C_t
- High breakdown voltage: $V_R = 80 \text{ V}$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	I_{F}	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward	I_{FSM}	500	mA
surge current *			
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s

Package

- Code
 - SMini2-F3
- Pin Name
 - 1: Anode
 - 2: Cathode

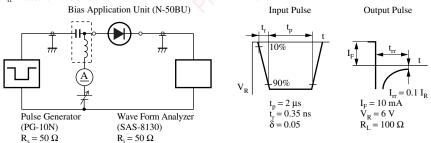
■ Marking Symbol: 1B

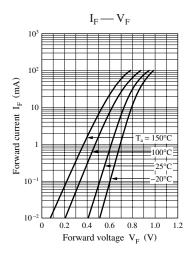
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

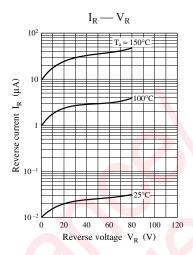
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 100 \text{ mA}$		0.95	1.20	V
Reverse voltage	V_R	$I_R = 100 \mu A$	80			V
Reverse current	I_R	V _R = 75 V			100	nA
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		0.6	1.2	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		$I_{rr} = 0.1 I_{R}$, $R_{L} = 100 \Omega$				

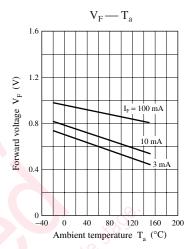
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

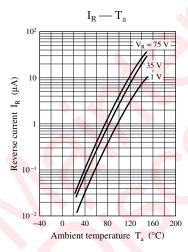
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *: t_{rr} measurement circuit

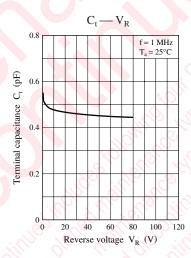


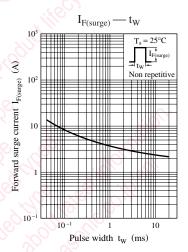






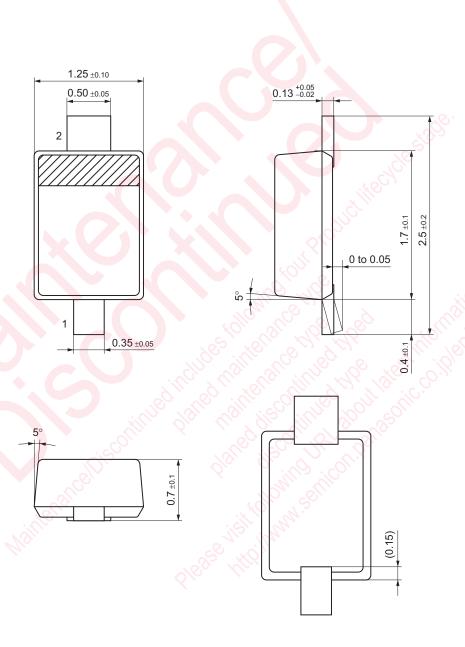






2 SKF00091AED

SMini2-F3 Unit: mm



SKF00091AED 3

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